

ECMF04-4HSM10

Common mode filter with ESD protection for high speed serial interface

Datasheet - production data

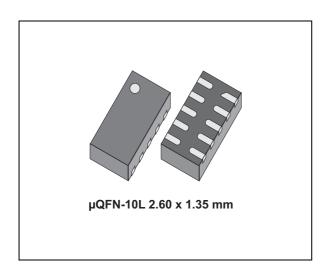
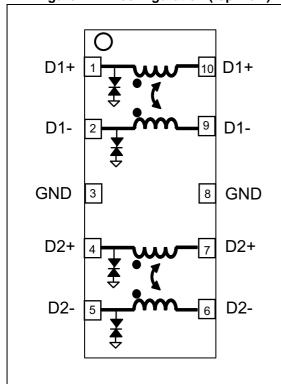


Figure 1. Pin configuration (top view)



Features

- Very large differential bandwidth to comply with HDMI Full HD, MIPI, USB2.0, USB3.0, Display Port and other high speed serial interfaces
- Provides -20 dB attenuation at 700 MHz in LTE bands
- High common mode attenuation:- 25 dB between 800 MHz - 900 MHz
- Very low PCB space consumption
- Thin package: 0.55 mm max.
- Lead-free package
- High reduction of parasitic elements through integration.

Complies with the following standards:

- IEC 61000-4-2 level 4:
 - ±15 kV (air discharge)
 - ±8 kV (contact discharge)

Applications

- Mobile phones
- Notebook, laptop
- Portable devices
- PND

Description

This device is a highly integrated common mode filter designed to suppress EMI/RFI common mode noise on high speed differential serial buses like HDMI Full HD, MIPI, Display Port and other high speed serial interfaces. The device has a very large differential bandwidth to comply with these standards. The device can protect and filter 2 differential lanes.

Characteristics ECMF04-4HSM10

1 Characteristics

Table 1. Absolute maximum ratings ($T_{amb} = 25 \text{ °C}$)

Symbol	Par	Value	Unit	
V _{PP}	Peak pulse voltage	IEC 61000-4-2 Contact discharge (connector side) Air discharge (connector side)	8 16	kV
I _{DC}	Maximum DC current		100	mA
T _{op}	Operating temperature range		-55 to +125	°C
Tj	Maximum junction temperature		125	°C
T _{stg}	Storage temperature range		-55 to +150	°C

Figure 2. Electrical characteristics (definitions)

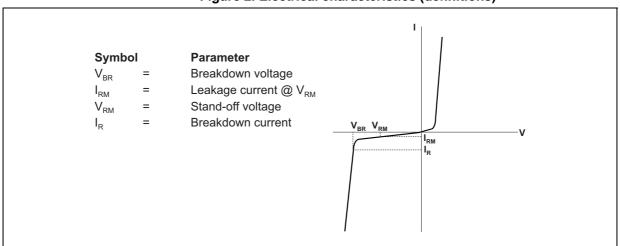


Table 2. Electrical characteristics (T_{amb} = 25 °C)

Symbol	Test conditions	Min.	Тур.	Max.	Unit
V _{BR}	I _R = 1 mA	6			V
I _{RM}	V _{RM} = 3 V per line			100	nA
R _{DC}	DC serial resistance		5		Ω

Table 3. Pin description

		_	
Pin number	Description	Pin number	Description
1	D1+ to connector	6	D2- to IC
2	D1- to connector	7	D2+ to IC
3	GND	8	GND
4	D2+ to connector	9	D1- to IC
5	D2- to connector	10	D1+ to IC

ECMF04-4HSM10 **Characteristics**

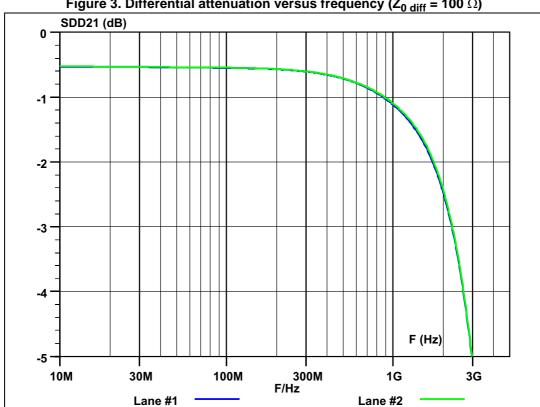
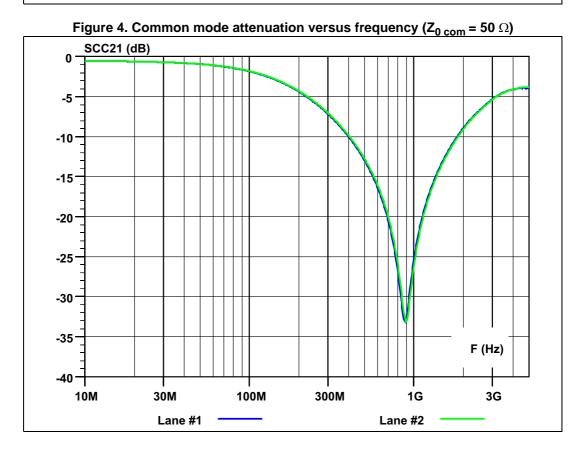


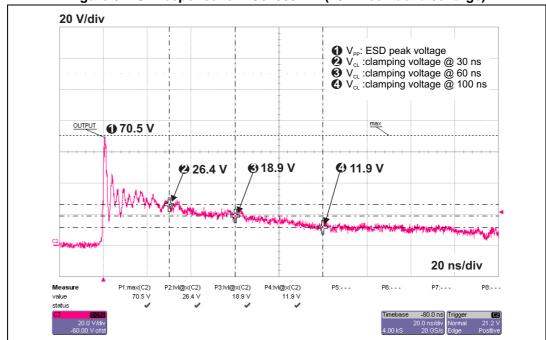
Figure 3. Differential attenuation versus frequency ($Z_{0 \text{ diff}}$ = 100 Ω)



Characteristics ECMF04-4HSM10

Figure 5. Differential (Z_{DD21}) and common mode (Z_{CC21}) impedance versus frequency





ECMF04-4HSM10 **Characteristics**

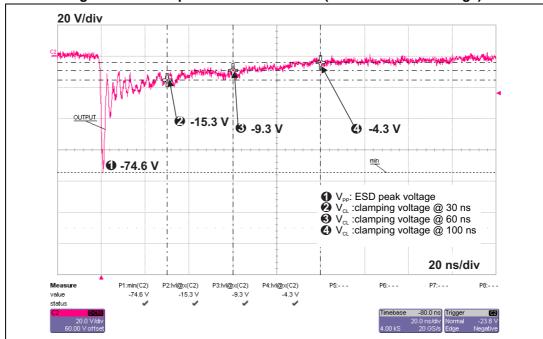


Figure 7. ESD response to IEC61000-4-2 (-8 kV contact discharge)

200 mV/c

347.2 ps/c

Thru

200 mV/c ECMF04-4HSM10 347.2 ps/c

Figure 8. USB2.0 480 Mbps eye diagram without Figure 9. USB2.0 480 Mbps eye diagram with device device

Characteristics ECMF04-4HSM10

Figure 10. USB3.0 5 Gbps eye diagram without device

Figure 11. USB3.0 5 Gbps eye diagram with device

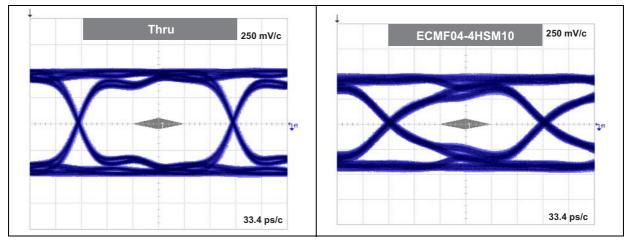
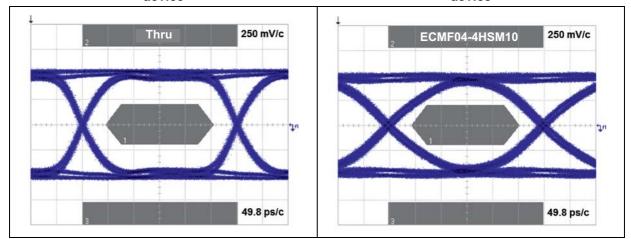


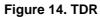
Figure 12. HDMI 3.35 Gbps eye diagram without device

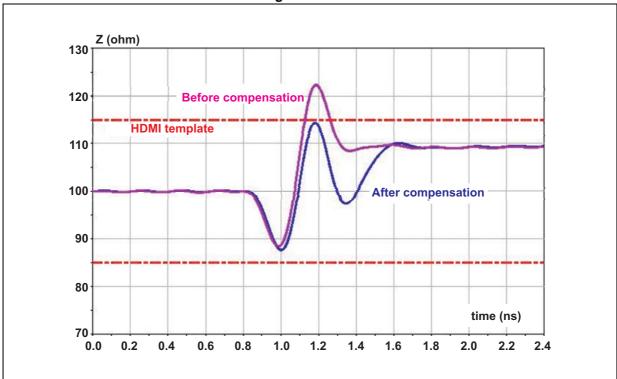
Figure 13. HDMI 3.35 Gbps eye diagram with device



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ECMF04-4HSM10 Characteristics





2 Application information

Figure 15. HDMI schematic

More application information available in following AN:

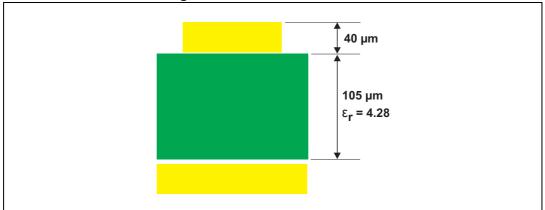
- Application Note AN4356: "Antenna desense on handheld equipment"
- Application Note AN4511: "Common Mode filters"
- Application Note AN4540: "MHL link filtering and protection"

PCB layout recommendations 3

Connector Host 5000 μm 350 µm 350 µm lanes $(Z_0 = 100 \Omega)$ $(Z_0 = 100 \Omega)$

Figure 16. PCB layout recommendations





Package information ECMF04-4HSM10

4 Package information

- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

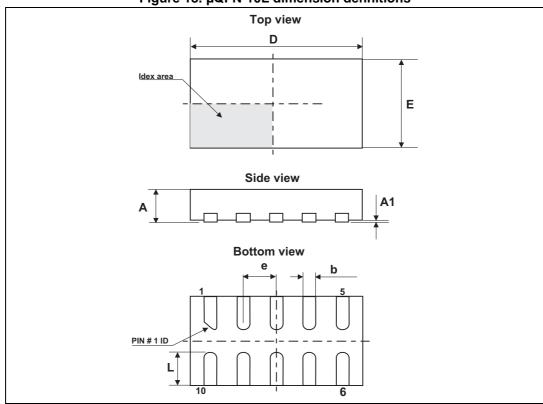


Figure 18. µQFN-10L dimension definitions

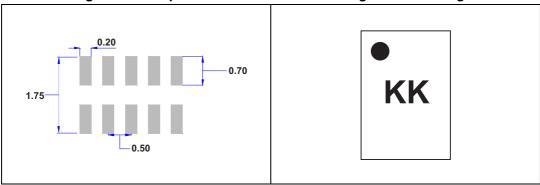
Table 4. µQFN-10L dimension values

	Dimensions						
Ref.	Millimeters			Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
А	0.45	0.50	0.55	0.018	0.020	0.022	
A1	0.00	0.02	0.05	0.00	0.0008	0.002	
b	0.15	0.20	0.25	0.006	0.008	0.010	
D	2.55	2.60	2.65	0.1	0.102	0.104	
Е	1.30	1.35	1.40	0.051	0.053	0.055	
е		0.50			0.020		
L	0.40	0.50	0.60	0.016	0.020	0.024	

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Figure 19. Footprint

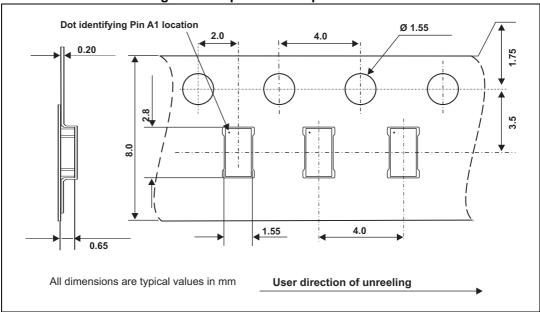
Figure 20. Marking



Note:

Product marking may be rotated by multiples of 90° for assembly plant differentiation. In no case should this product marking be used to orient the component for its placement on a PCB. Only pin 1 mark is to be used for this purpose.

Figure 21. Tape and reel specifications



Ordering information ECMF04-4HSM10

5 Ordering information

Figure 22. Ordering information scheme

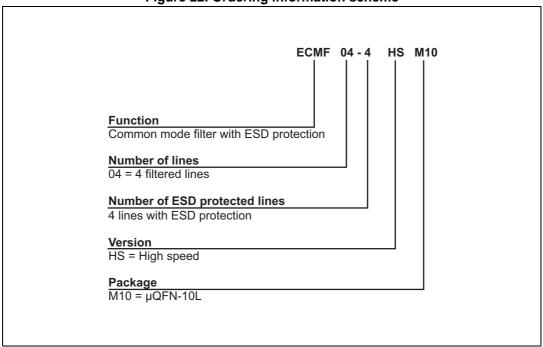


Table 5. Ordering information

Order code	Marking ⁽¹⁾	Package	Weight	Base qty	Delivery mode
ECMF04-4HSM10	KK	μQFN-10L	5.00 mg	3000	Tape and reel

^{1.} The marking can be rotated by multiples of 90° to differentiate assembly location

6 Revision history

Table 6. Document revision history

Date	Revision	Changes
03-Oct-2013	1	Initial release.
25-Aug-2014	2	Added Figure 5: Differential (ZDD21) and common mode (ZCC21) impedance versus frequency.
13-Dec-2017	3	Updated Table 1.

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